

Test	Condition	Description	Reference Standard
Operating Life Test	<ul style="list-style-type: none"> Under Room Temperature If=20mA t=1000hrs(-24hrs,72hrs) 	This test is conducted for the purpose of determining the Resistance of a part in electrical and thermal stressed.	MIL-STD-750:1026 MIL-STD-883:1005 JIS C 7021:B-1
High Temperature Storage Test	<ul style="list-style-type: none"> Ta=105°C ± 0.5°C t=1000hrs(-24hrs,72hrs) 	The purpose of this test is the resistance of the device which Is laid under condition of high temperature for hours.	MIL-Std-883:1008 JIS C 7021:B-10
Low Temperature Storage Test	<ul style="list-style-type: none"> Ta=-40°C±0.5°C t=1000hrs(-24hrs,72hrs) 	The purpose of this test is the resistance of the device which Is laid under condition of low temperature for hours.	JIS C 7021:B-12
High Temperature High Humidity Test	<ul style="list-style-type: none"> Ta=65°C±0.5°C RH=90%~95% t=240hrs±2hrs 	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021:B-11
Thermal Shock Test	<ul style="list-style-type: none"> 105°C±0.5°C&-40°C±0.5°C (10min)(10min) total 10 cycles 	The purpose of this test is the resistance of the device to Sudden extreme changes in high and low temperature.	MIL-STD-202:103B MIL-STD-750:1051 MIL-STD883:1011
Solder Resistance Test	<ul style="list-style-type: none"> T. Sol=260°C±0.5°C Dwell solder 10±1sec 	This test is intended to determine the thermal characteristic Resistance of the device to sudden exposures at extreme Changes in temperature when soldering the lead wire.	MIL-STD-2025:210A MIL-STD-750:2031 JS C 7021:A-1
Solder ability Test	<ul style="list-style-type: none"> T. Sol=230°C±0.5°C Dwell time=5±1sec. 	This test intended to see soldering well performed or not	MIL-STD-202:208D MIL-STD-750:2026 MIL-STD-883:2003 JIS C 7021:A-2

- All specifications in this short form are subject to change without prior notice. Please contact us for updated data sheet.